ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	annockburn, Illinois, A	All rights reserved untions.	Inder both	This docume evel parts, th	ent is a declaration he declaration er	on of the subs acompasses a	stances w Ill lower	vithin the manufactu level materials for w	rer listed	item. Note: nanufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
	P1.1 IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and N	als and Mfg Information			
Supplier Information													
Company name* Company unique ID				Unique ID Authority				Response Date*					
nsemi									2025-06-06				
Contact Name	Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Co			o Compliance		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
P	MUN2235T1G	235T1G NPN Digital Transistor			2025-06-06					11.03	mg	Each	
Manufacturing Proccess Information											· · ·		
Terminal Plating / Grid Array Material	Terminal Base	Terminal Base Alloy J-STI		Rating	Peak Process Body Temperat		perature	ure Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy			1		260	C	2	30	seco	nds 3			
Comments													
evel 1 - maximum time at peak temperature du	uring soldering is 10-	30 seconds											
or more information regarding material comp	position please refer t	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).				-	_		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.22	mg	Supplier	Silicon (Si)	7440-21-3		0.22	mg
Lead Frame 3	3.06	mg	В	Nickel (Ni)	7440-02-0		1.2393	mg
			Supplier	Iron (Fe)	7439-89-6		1.6983	mg
			Supplier	Copper (Cu)	7440-50-8		0.1224	mg
Mold Compound-Black	7.13	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.713	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0356	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.0338	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.6345	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.713	mg
Plating	0.52	mg	Supplier	Tin (Sn)	7440-31-5		0.52	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg